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# Combining nanoindentation with complementary techniques for mechanical and structural characterization of ultra uow-k (ULK) thin films

Andre Clausner

*Fraunhofer IKTS-MD*, [andre.clausner@ikts-md.fraunhofer.de](mailto:andre.clausner@ikts-md.fraunhofer.de)

Ehrendried Zschech

*Fraunhofer IKTS-MD*

Martin Gall

*Fraunhofer IKTS-MD*

Yvonne Standke

*Fraunhofer IKTS-MD*

Malgorzata Kopycinska

*Fraunhofer IKTS-MD*

*See next page for additional authors*

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**Authors**

Andre Clausner, Ehrendried Zschech, Martin Gall, Yvonne Standke, Malgorzata Kopycinska, Kong Boon Yeap, Khashayar Pakbaz, Reinhard Krause-Rehberg, and Dieter Schneider





# Combining indentation with complementary techniques for mechanical and structural characterization of ULK thin films

André Clausner<sup>1</sup>, Martin Gall<sup>1</sup>, Yvonne Standke<sup>1</sup>, Rüdiger Rosenkranz<sup>1</sup>, Ehrenfried Zschech<sup>1</sup>, Malgorzata Kopycinska-Mueller<sup>1</sup>, Kong Boon Yeap<sup>2</sup>, Khashayar Pakbaz<sup>3</sup>, Reinhard Krause-Rehberg<sup>4</sup>, Dieter Schneider<sup>5</sup>, Ude Hangen<sup>6</sup> and Anqi Qiu<sup>6</sup>

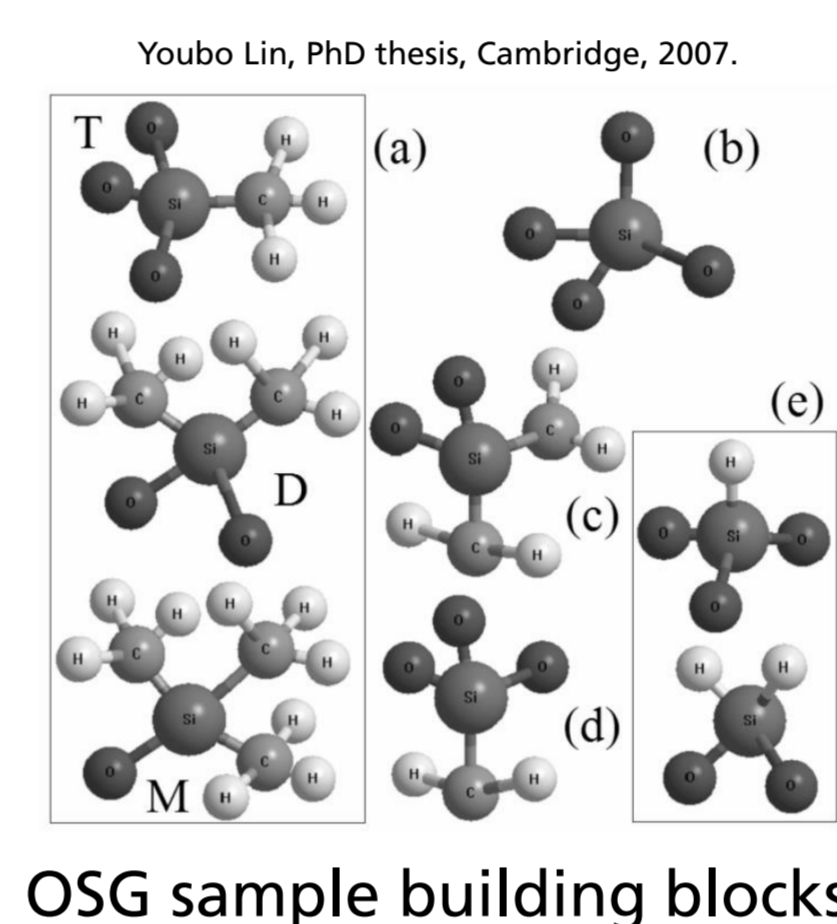
1: Fraunhofer IKTS, Dresden, Germany (andre.clausner@ikts.fraunhofer.de); 2: GLOBALFOUNDRIES, Malta, USA; 3: SBA Materials, Albuquerque, USA; 4: Martin Luther University, Halle, Germany; 5: Fraunhofer IWS, Dresden, Germany; 6: Hysitron Inc., Minnesota, USA

## 1. MOTIVATION

Nano-porous dielectrics (ULKs) used as insulating materials between on-chip interconnects are an important component in metallization stacks of leading-edge microelectronic products to reduce electrical signal delay and power loss. The main drawbacks of these porous dielectrics are their weak mechanical properties. The main part of this study are the experimental techniques used for mechanical and structural analysis of the organosilicate glasses (OSGs). Mechanical characterization is done using nanoindentation (NI) and is complemented by atomic force acoustic microscopy (AFAM) as well as surface acoustic wave (SAW) measurements.

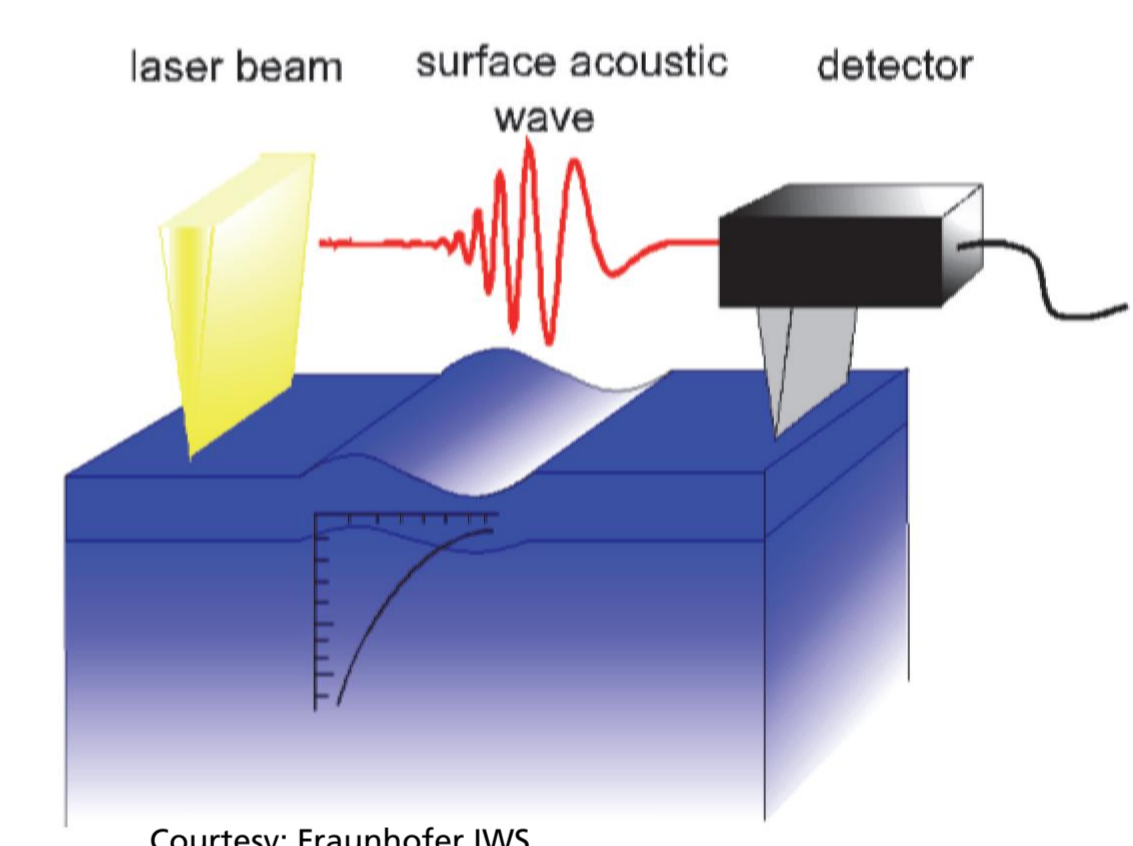
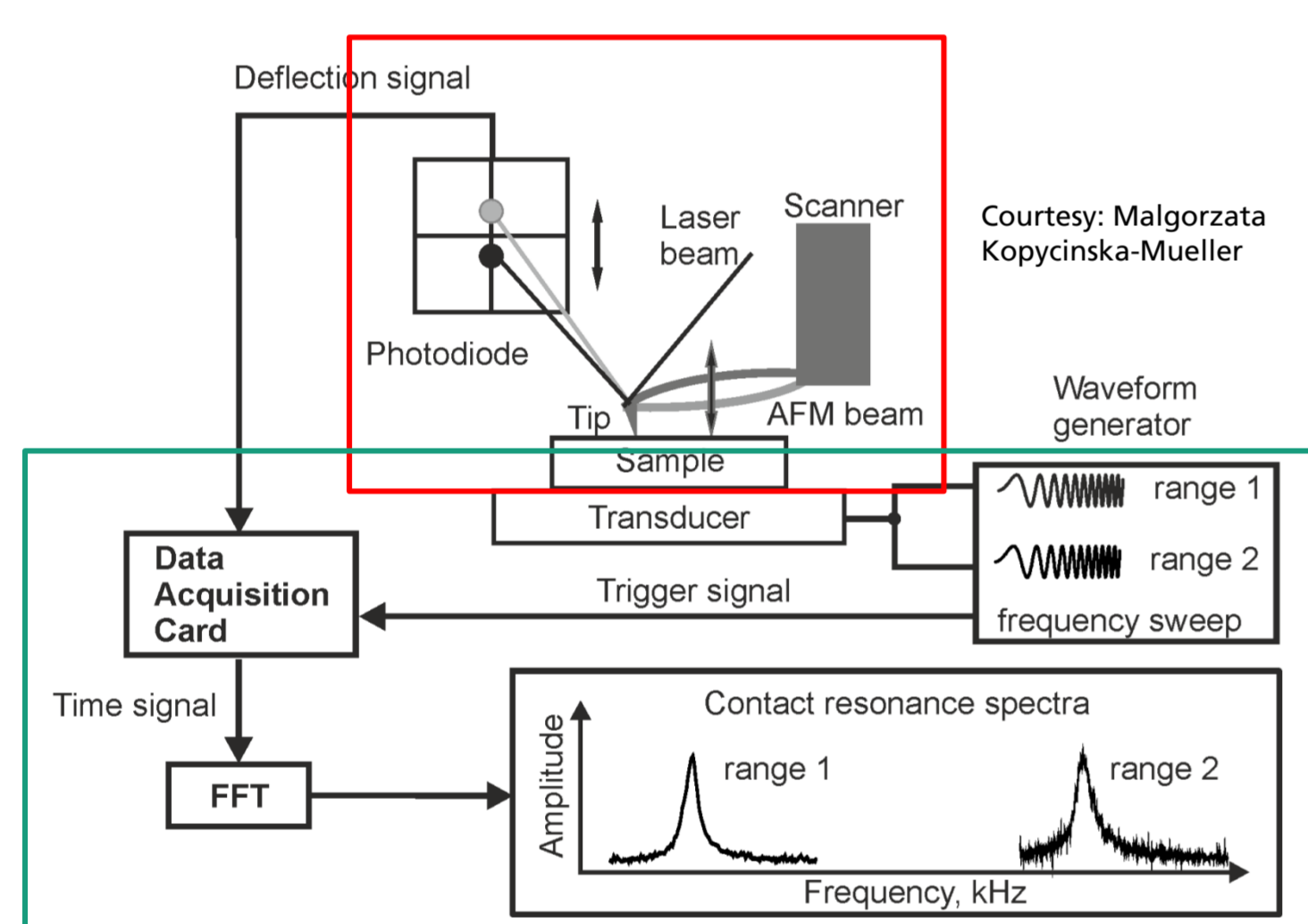
## 2. MATERIALS

Studied are new types of porous organosilicate glasses (OSGs) exhibiting a highly ordered pore arrangement. The OSGs were produced by SBA materials using a sol gel spin on process and different amounts of porogens.



| Sample | film thickness t/nm | Porosity p/% | dielectric constant k |
|--------|---------------------|--------------|-----------------------|
| 1      | 517                 | 54           | 1,8                   |
| 2      | 510                 | 42           | 2,1                   |
| 3      | 533                 | 30           | 2,3                   |
| 4      | 527                 | 25           | 2,5                   |
| 5      | 489                 | 17           | 2,7                   |
| 6      | 441                 | 0            | 3,1                   |

## 3. EXPERIMENTAL TECHNIQUES AND RESULTS



### Atomic Force Acoustic Microscopy (AFAM)

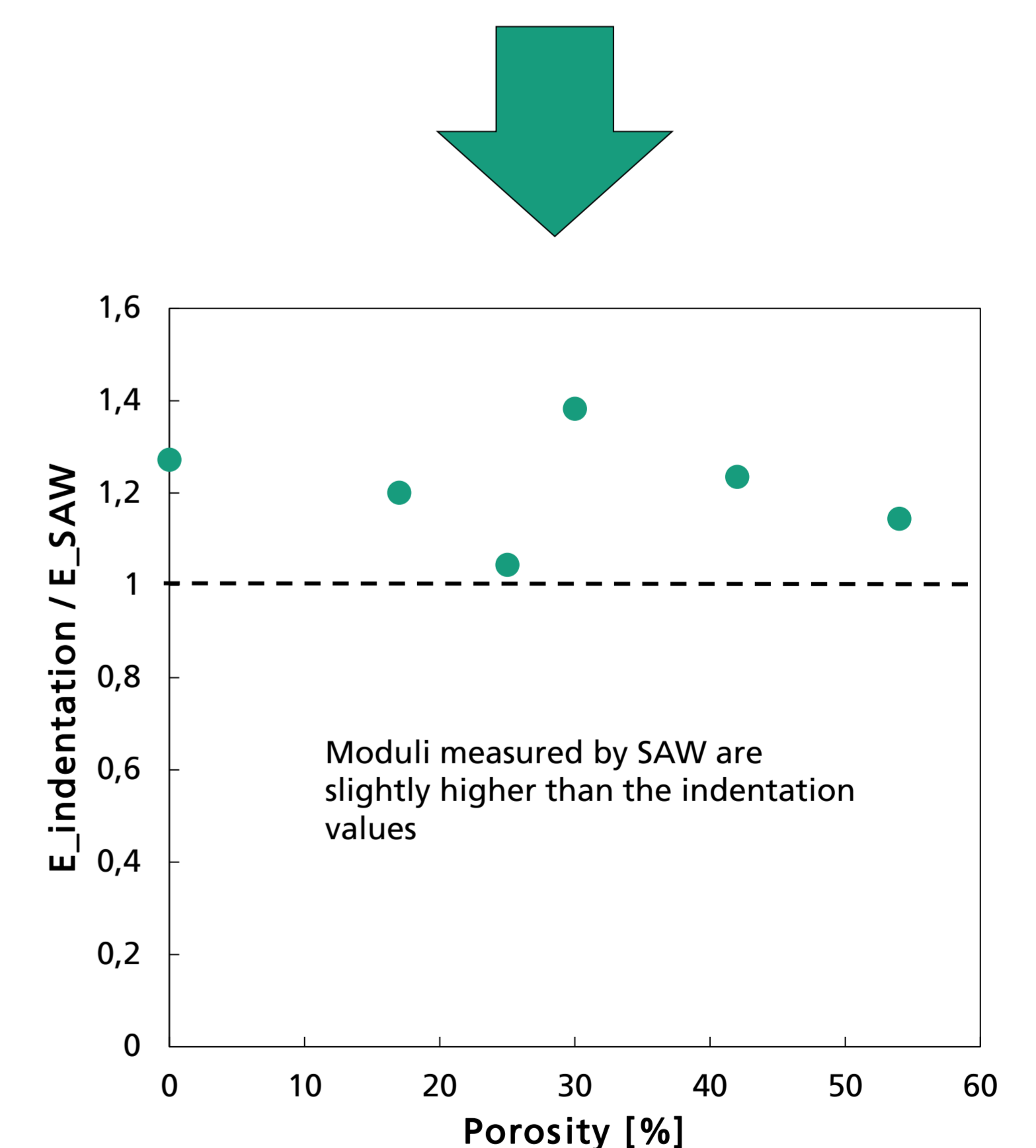
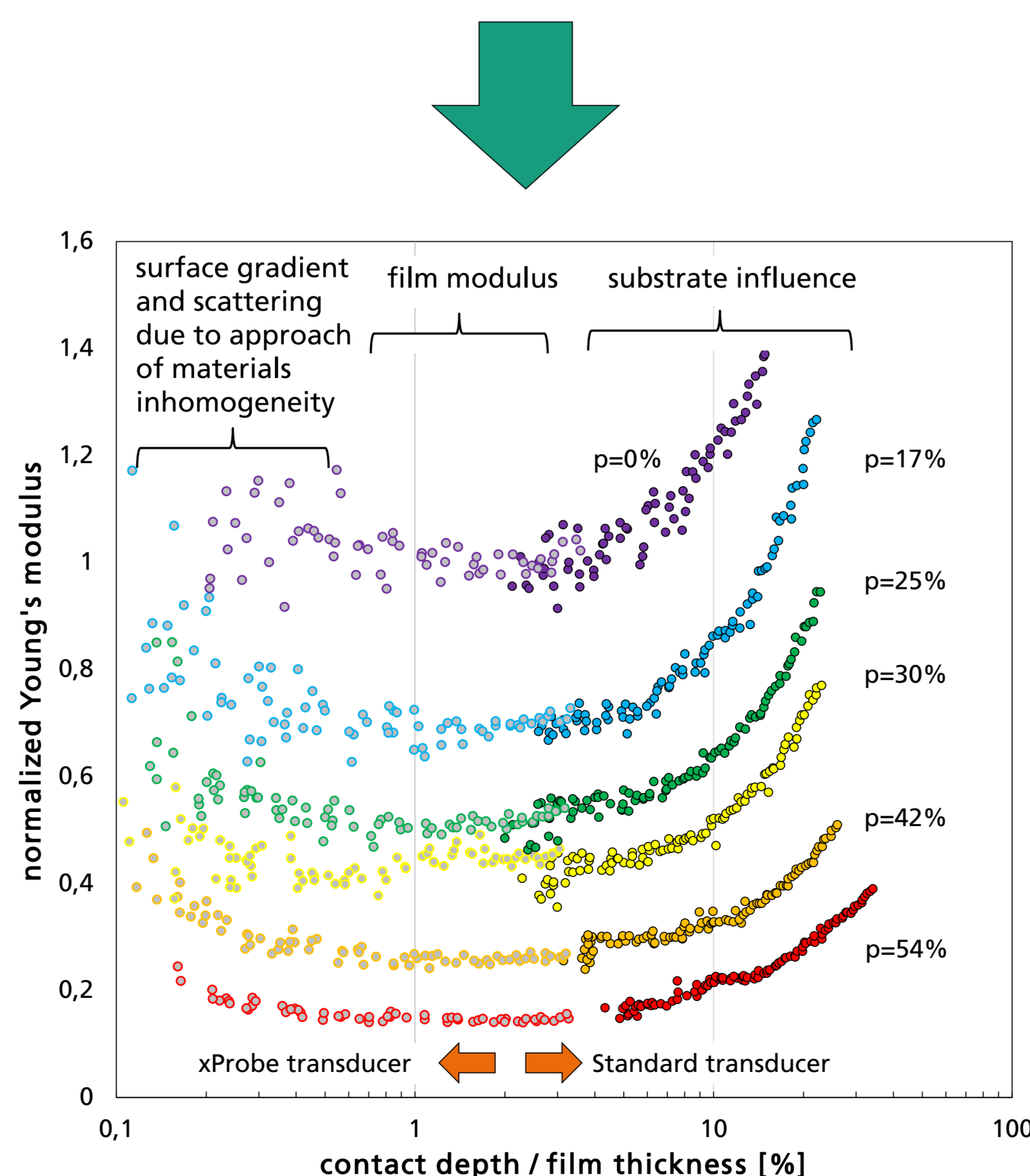
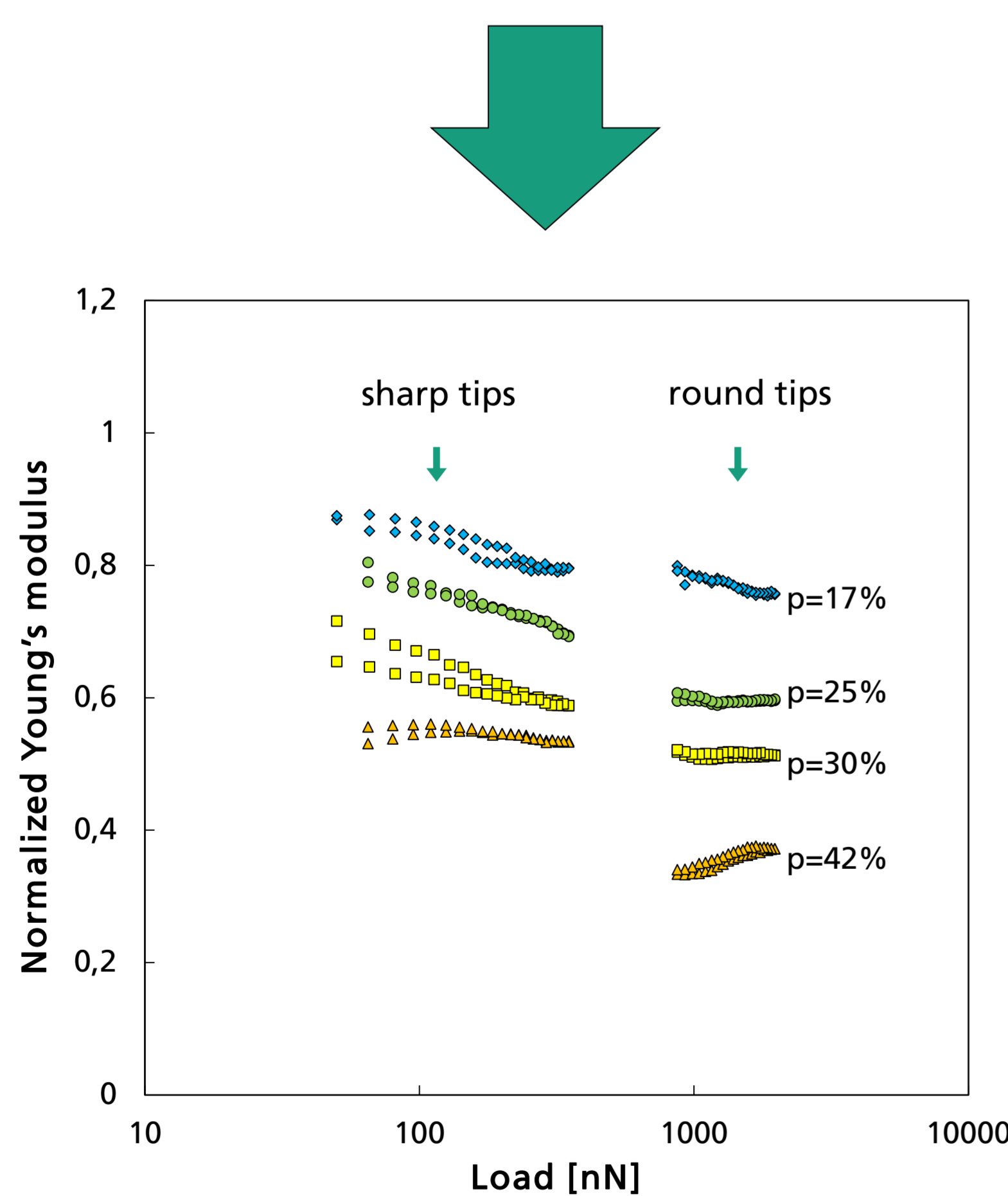
- AFM in contact mode coupled with a frequency generator
- See also: Kopycinska-Mueller et al., Nanotechnology 24, 2013

### High resolution nanoindentation using the Hysitron Xprobe

- xProbe: high resolution MEMS nano-indentation transducer
- Basic principles of nanoindentation: Oliver, Pharr, J. Mater. Res. 7, 1992

### Surface Acoustic Waves (SAW)

- Measuring speed of sound by laser induced lateral elastic waves



## 4. CONCLUSIONS

- ✓ Using AFAM, very shallow surface gradients become visible.
- ✓ Using the high resolution Hysitron xProbe in addition to the standard transducer enables the measurement of substrate influence free moduli of thin films.
- ✓ Using the xProbe, even the surface gradient in the modulus, seen using AFAM, becomes accessible using nanoindentation
- ✓ The visible surface gradient could be due to the measurement of the material's backbone rather than its global compliance at low indentation depths
- ✓ SAW measurements give slightly higher moduli compared to indentation, maybe due to anisotropy of the material